Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6	\$3mold\$3 adj MCM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/02 13:11
S1	115	"5218344"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/02 13:09
S2	43	"5399903"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 18:50
S3	934	(solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:12
S4	56	(solder adj1 mask) and (trench or recess or cavity) and MCM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S6		(solder adj1 mask) and (solder adj1 mask adj1 (trench or recess or cavity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/15 18:55
S7	41	"5579207"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 10:52
S8	2	"6288909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/17 10:52
S9	3	("4857989"   "4926240"   "5091770").PN. OR ("6614122"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/09 13:57
S15	4	361/743 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59

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S16	1	361/745 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S17	20	361/748 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S18	37	361/749 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2005/02/09 14:16
S19	. 4	361/750 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S20	7	361/751 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S22	46	361/761 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S23	25	361/762 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S24	. 45	361/764 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S25	12	361/736 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S26	12	361/728 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/09 14:19

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S27	79	174/260 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S28	48	174/250 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S29	22	174/263 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S30	55	174/262 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S31	41	174/52.2 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S34	3	(solder adj1 mask adj1 (trench or recess or cavity)) and mold\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/31 16:55
S36	2	(solder adj1 mask adj1 (trench or recess or cavity)) and underfill	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:08
S37	6	(solder adj1 mask adj1 (trench or recess or cavity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:10
S38	47	("3657610"   "4191905"   "4266156"   "4405875"   "4604644"   "4661192"   "4699682"   "4734608"   "4736128"   "4737742"   "4864470"   "4993000"   "5014111"   "5090119"   "5095240"   "5120678"   "5252882"   "5281883"   "5359494"   "5390401"   "5438305"   "5459368"   "5471722"   "5504980"   "5900581").PN. OR ("5969461").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/10 15:18

S39	72	361/760 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF.	2005/02/10 15:25
S40	90	174/52.2 and SAW	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:35
S41	56	174/52.2 and SAW and mold\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:35
S42	23	("4218701"   "4509096"   "4604644"   "4725924"   "4734818").PN. OR ("4864470").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/10 15:46
S43	2	310/313R and (solder adj1 mask)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/10 15:50
S44		2003/0218872	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/15 14:13
S45	2	"20030218872"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/15 14:13
S46	7	(solder adj1 mask adj1 (trench or recess or cavity)) and ((circuit adj1 board) or (substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/31 17:02
S47	1	"20030104657"	US-PGPUB	OR	OFF	2005/03/31 17:02
S48	2	361/750.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:23
S49	10	361/760.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:26

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S50	2	361/736.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:32
S51	3	361/748.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:32
S52	2	361/751.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:33
S53	6	361/762.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:37
S54	1	361/765.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:39
S55	. 1	361/766.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:39
S56	10	361/767.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:39
S58	2	361/792.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:44
S59	1	361/790.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:44
S60	3	361/793.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:44

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S61	4	361/795.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:45
S62	8	174/250.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:45
S63	. 3	174/251.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:50
S64		174/255.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:52
S65	7	174/256.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:22
S66	6	174/257.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:22
S67	9	174/258.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:23
S68	4	174/259.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:23
S69	. 31	174/260.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:23
S70	3	174/263.ccls. and (solder adj1 mask adj1 layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 17:23

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S71	82	(solder adj1 mask) and (trench or recess or cavity) and MCM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S72	4	361/743 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S73		361/745 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S74	26	361/748 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S75	5	361/750 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S76	7	361/751 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S77	. 47	361/761 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 08:59
S78	27	361/762 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR ·	OFF	2006/05/16 08:59
S79	47	361/764 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S80	13	361/736 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00

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S81	93	174/260 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S82	52	174/250 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S83		174/263 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S84	63	174/262 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S85	47	174/52.2 and (solder adj1 mask) and (trench or recess or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/16 09:00
S86	10	("5311405"   "6150193"   "6177731"   "6228466"   "6245594"   "6294840"   "6388335"   "6448644").PN. OR ("6521997"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/20 17:19
S87	24	"6399906"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	OFF	2006/12/21 11:16
S88	27	("3283107"   "6039599"   "6059592"   "6073853"   "6129571").PN. OR ("6399906").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/21 11:17
S89	8	("4397513"   "5016086"   "5402385"   "5539600"   "6145023"   "6170743"   "6399906"   "6590778").PN. OR ("6947289"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/21 11:29
S90	9	("4397513"   "5016086"   "5402385"   "5539600"   "6145023"   "6170743"   "6399906"   "6580615"   "6590778").PN. OR ("6922343"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/21 11:30

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S91	19	("3283107"   "5820391"   "5911587"   "6004155"   "6015311"   "6039599"   "6059592"   "6073853"   "6099335"   "6126464"   "6129571"   "6399906").PN. OR ("6638087").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/21 11:36
S92	5	"4882838"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/22 18:10
S93	2	"5941735"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/12/22 18:10
S94	9	("3813637"   "4191440"   "4747784"   "5147228"   "5211579"   "5395263"   "5667412"   "5820406"   "5879203").PN. OR ("5941735"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/12/22 18:11

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